



SOT-23



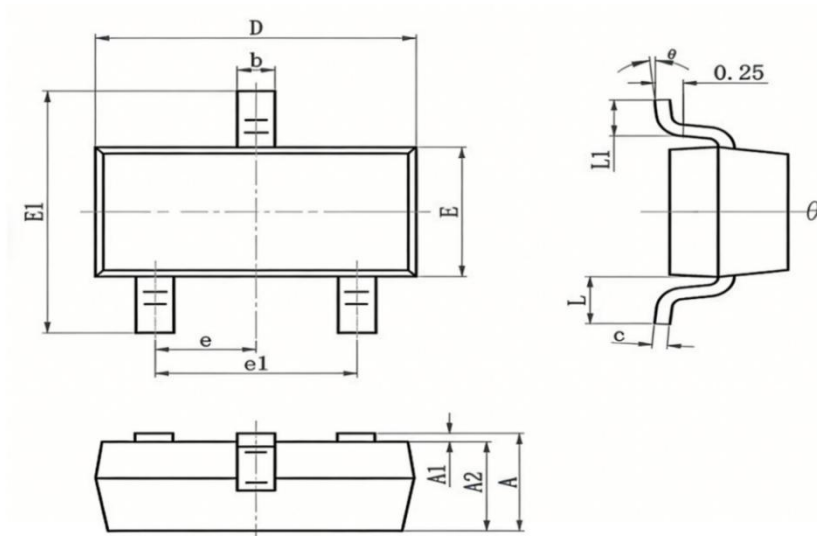
**Plastic, surface-mounted package; 3 terminals;
1.9 mm pitch; 2.9 mm x 1.3 mm x 1 mm body**
塑料表面贴装封装；3 引脚；间距 1.9 mm；
封装本体尺寸 2.9 mm x 1.3 mm x 1 mm

1. Mechanical Data 封装数据

Feature 特性	Description 描述
Package 封装	SOT-23
Moisture Sensitivity Level 湿敏感度等级	J-STD-020 MSL1
Mounting Method Type 安装方式类型	Surface Mount Package 表面贴装封装
Material 材料	Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0. 模塑塑料封装，“绿色”成型复合材料；UL 可燃性等级 94V-0。
Dimensions 尺寸	1.9mm pitch; 2.9mm × 1.3mm × 1.0mm body 相邻引脚中心距为 1.9mm，封装本体（不含引脚）尺寸为 2.9mm × 1.3mm × 1.0mm
Terminals Compliance 引脚合规	3 terminals, Tin Plated Leads, Solderable per MILSTD-202, Method 208 ^③ 3 个镀锡引脚，可焊性符合 MIL-STD-202 标准中 208 方法 e3 条款的要求
Weight 重量	0.008 grams (Approximate) 约 0.008 克

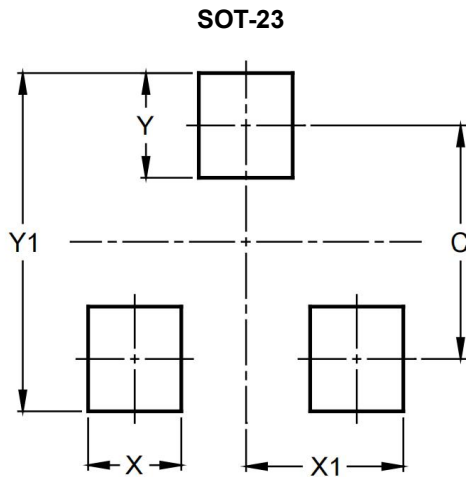
2. Package Outline Dimensions 封装外形尺寸

SOT-23



Symbol 符号	Millimeters 毫米	
	Min.最小值	Max.最大值
A	0.900	1.150
A1	0	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.900	1.000
e1	1.800	2.000
L	0.500	0.600
L1	0.300	0.500
θ	0°	8°

3. Suggested Pad Layout 推荐焊盘布局



Dimensions 尺寸	Millimeters 毫米
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

Fig. Soldering footprint for SOT-23

图 SOT-23 的引脚焊接

4. Minimum Packing Quantity 最小包装数量

Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
7	8	3000

Note:

Package quantities given are for minimum packaging quantity only, not minimum order quantity. For minimum order quantity, please contact Sales Department.

说明: 上表所列包装数量仅为最低包装数量，并非最低订购数量。如需最低订购数量，请联系销售部门。



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